

1473005-4 ✓ ACTIVE



## DDR2 SO DIMM

TE Internal #: 1473005-4

SO DIMM Sockets, Double Data Rate (DDR) 2, Stack Height .205 in [5.2 mm], Right Angle Module Orientation, 200 Position, DDR2 SO DIMM

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DRAM Type: **Double Data Rate (DDR) 2**

Stack Height: **5.2 mm [ .205 in ]**

Module Orientation: **Right Angle**

Connector System: **Cable-to-Board**

Number of Positions: **200**

[All DDR2 SO DIMM Sockets \(30\)](#)

## Features

### Product Type Features

|                                   |                          |
|-----------------------------------|--------------------------|
| DRAM Type                         | Double Data Rate (DDR) 2 |
| Connector System                  | Cable-to-Board           |
| Connector & Contact Terminates To | Printed Circuit Board    |

### Configuration Features

|                     |             |
|---------------------|-------------|
| Number of Bays      | 2           |
| Number of Keys      | 1           |
| Number of Rows      | 2           |
| Module Orientation  | Right Angle |
| Number of Positions | 200         |

### Electrical Characteristics

|              |       |
|--------------|-------|
| DRAM Voltage | 1.8 V |
|--------------|-------|

### Signal Characteristics



|               |       |
|---------------|-------|
| SGRAM Voltage | 1.8 V |
|---------------|-------|

### Body Features

|                        |                 |
|------------------------|-----------------|
| Ejector Location       | Both Ends       |
| Latch Material         | Stainless Steel |
| Latch Plating Material | Tin             |
| Module Key Type        | SGRAM           |
| Ejector Type           | Locking         |
| Connector Profile      | Standard        |

### Contact Features

|   |              |
|---|--------------|
| Memory Socket Type                            | Memory Card  |
| PCB Contact Termination Area Plating Material | Gold Flash   |
| Contact Base Material                         | Copper Alloy |
| Contact Mating Area Plating Material          | Gold Flash   |
| Contact Current Rating (Max)                  | .5 A         |

### Termination Features

|                 |        |
|-----------------|--------|
| Insertion Style | Cam-In |
|-----------------|--------|

### Mechanical Attachment

|                          |                 |
|--------------------------|-----------------|
| Mating Alignment Type    | Standard Keying |
| PCB Mounting Style       | Surface Mount   |
| PCB Mount Retention      | With            |
| PCB Mount Retention Type | Solder Peg      |
| Connector Mounting Type  | Board Mount     |

### Housing Features

|                    |                                |
|--------------------|--------------------------------|
| Housing Material   | High Temperature Thermoplastic |
| Housing Color      | Black                          |
| Centerline (Pitch) | .6 mm[.024 in]                 |

### Dimensions

|                    |                 |
|--------------------|-----------------|
| Stack Height       | 5.2 mm[.205 in] |
| Row-to-Row Spacing | 6.2 mm[.244 in] |

### Usage Conditions

|                             |                           |
|-----------------------------|---------------------------|
| Operating Temperature Range | -55 – 85 °C[-67 – 185 °F] |
|-----------------------------|---------------------------|

### Operation/Application



|                     |       |
|---------------------|-------|
| Circuit Application | Power |
|---------------------|-------|

### Industry Standards

|                        |          |
|------------------------|----------|
| UL Flammability Rating | UL 94V-0 |
|------------------------|----------|

### Packaging Features

|                    |                         |
|--------------------|-------------------------|
| Packaging Quantity | 20                      |
| Packaging Method   | Semi-Hard Tray Assembly |

### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

|   |   |
|---|---|
| EU RoHS Directive 2011/65/EU                  | Compliant   |
| EU ELV Directive 2000/53/EC                   | Compliant   |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold   |
| EU REACH Regulation (EC) No. 1907/2006        | Current ECHA Candidate List: JUNE 2023 (235)<br>Candidate List Declared Against: JUNE 2023 (235)<br>Does not contain REACH SVHC |
| Halogen Content                               | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free   |
| Solder Process Capability                     | Reflow solder capable to 245°C  |

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

### Compatible Parts



TE Part # 2309407-1  
DDR4 SODIMM 260P 4.0H STD

TE Part # 1871233-4  
DDR2 H5.2 REV DIRECT PEG TRAY ASS'Y


TE Part # 1932317-4  
EMBOSS ASSY DDR2 SODIMM SOCKET 200P 9.2H

TE Part # 1932317-6  
EMBOSS ASSY DDR2 SODIMM SOCKET 200P 9.2H

TE Part # 1932208-1  
EMBOSS TAPE DDR3 204P 5.2H RVS

TE Part # 1932210-1  
EMBOSS TAPE DDR3 204P 9.2H RVS

### Also in the Series | **DDR2 SO DIMM**



SO DIMM Sockets(24)

### Customers Also Bought



TE Part #5-1614884-3  
CPF 0805 360R 0.1% 25PPM 1K RL



TE Part #7-1624113-1  
3650 2A 2.2uH 5% 2K RL



TE Part #2344655-2  
PCB ANT, MHF, 100mm, Wi-Fi TRIPLE BAND



TE Part #T2030012040-000  
DEF-4.0



TE Part #4-2176251-0  
CRGS2010 5% 1K8

TE Part #2846513-1  
64CX44AWG\_Sonoscanner Assembly



## Documents

### Product Drawings

[SEMI-HARD TRAY DDR2 SODIMM SOCKET 200P 5](#)

English

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### CAD Files

Customer View Model

[ENG\\_CVM\\_CVM\\_1473005-4\\_J1.2d\\_dxf.zip](#)

English

3D PDF

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_1473005-4\\_J1.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_1473005-4\\_J1.3d\\_stp.zip](#)

English

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### Product Specifications

[Product Specification](#)

English

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### Product Environmental Compliance

[Product Compliance Document](#)

English

[Product Compliance Document](#)

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